

## 10/100/1000 BASE-T MAGNETICS MODULES

### MODEL NO.: IH-019(Bottom Open)

#### FEATURE:

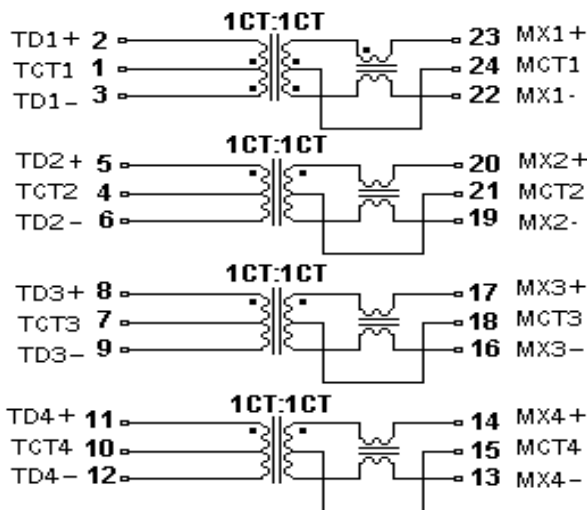
- RoHS Compliant
- RoHS peak solder rating 260°C/ 3~5 Sec
- Designed to meet IR requirement
- Operating temp. : -40°C ~ +85°C

#### SPECIFICATION @ 25°C

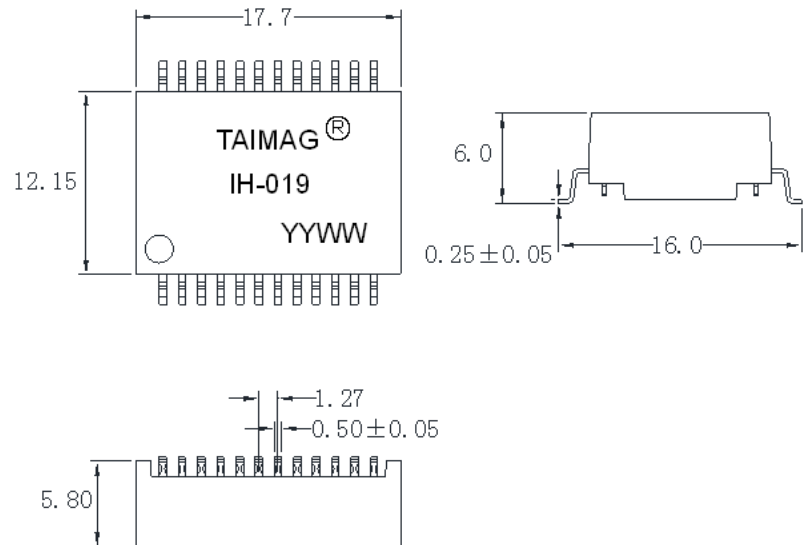
OCL : 350 uH Min @100kHz ,100mv 8mA DC Bias

Turns Ratio (±3%)	Insertion Loss (dB MAX)	Cross Talk (dB MIN)			Return Loss (dB MIN)					DCMR (dB MIN)			HIPOT (VAC)
		30	60	100MHz	1~40	50	60	80	100MHz	1-30	60	100MHz	
TX/RX	1~100MHz	30	60	100MHz	1~40	50	60	80	100MHz	1-30	60	100MHz	1500
1CT:1CT	-1.0	-45	-40	-35	-18	-14.4	-13.1	-12	-10	-43	-37	-33	

#### SCHEMATICS:



#### DIMENSION: mm TOLERANCE:±0.25



DATE CODE:YY=YEAR  
WW=WEEK

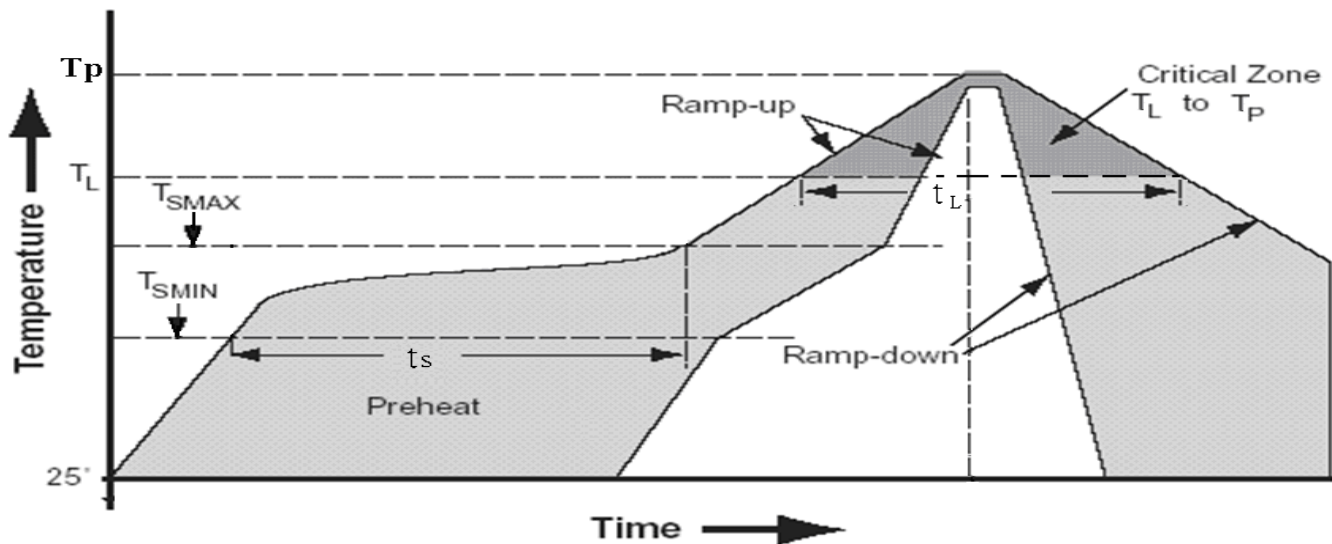
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Solder Reflow profile for Lead-Free packages.  
Package Peak Reflow Temperatures

### Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate( $T_L$ to $T_P$ )	3°C / Second Max.	
Preheat Temperature Min.( $T_s$ min.) Temperature Max.( $T_s$ max.) Time (min to max) ( $t_s$ )	150 °C 200 °C 60-180 sec	
$T_s$ max. to $T_L$ Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature ( $T_L$ ) Time ( $t_L$ )	200 °C 60-90 sec	
Peak Temperature ( $T_p$ ) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

## Profile



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### PACKING:

1. Tape & Reel : 400pcs / Reel , 2000pcs / Carton
2. Dry Pack : 1pcs  
Product Description:(5g Silica Gel Desiccant)  
PH: 4-8  
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum
4. Seal Per JEDEC

